

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"20040061240".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L2	3419	(257/778).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/03 21:00
L3	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L4	0	L3 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L5	434	L2 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L6	323	L2 and substrate with tape	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L7	88	L6 and underfill	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L8	180	("4604644" / "4825284" / "4970575" / "4987100" / "5107325" / "5177669" / "5222014" / "5239198" / "5249101" / "5291062" / "5311402").PN. OR ("5450283").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00

L9	43	L2 and surfactant	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L10	1	"6,576,495".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L11	2596	tape with substrate with made	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L12	699	L11 and "257"/\$. cc1s.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L13	12	("5918364" / "5939783" / "5985456" / "6013417" / "6044550" / "6165885" / "6281046" / "6316830" / "6319751").PN. OR ("6445075").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L14	3	(US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did.	USPAT	OR	ON	2008/02/03 21:00
L15	143	lead with substrate with bump and 257/778.cc1s.	USPAT	OR	ON	2008/02/03 21:00
L16	6	("4624724" / "5538771" / "5614316" / "5670251").PN. OR ("6498400").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L17	24	("2671844" / "3488840" / "4661192" / "4706811" / "4758407" / "4806309" / "5120678" / "5154341" / "5269453" / "5282565" / "5346857" / "5352407" / "5410184" / "5411703" / "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L18	20	("4706811" / "4758407" / "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L19	95	lead with substrate with bump and 257/738.cc1s.	USPAT	OR	ON	2008/02/03 21:00

L20	95	lead with substrate with bump and 257/738.ccls.	USPAT	OR	ON	2008/02/03 21:00
L21	14	lead with substrate same underfill and 257/738.ccls.	USPAT	OR	ON	2008/02/03 21:00
L22	5	lead with substrate same underfill same bump same solder near (resist layer)	USPAT	OR	ON	2008/02/03 21:00
L23	8	("5349238"   "5442229"   "5825081"   "6603071"   "6744120").PN. OR ("6867490").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L24	7	lead with bump same underfill same bump same solder near (resist layer)	USPAT	OR	ON	2008/02/03 21:00
L25	7	lead with bump same underfill same solder near (resist layer)	USPAT	OR	ON	2008/02/03 21:00
L26	12818	lead with bump same solder near (resist layer)	USPAT	OR	ON	2008/02/03 21:00
L27	5383	lead with bump same solder near (resist layer)and 257/738. ccls.	USPAT	OR	ON	2008/02/03 21:00
L28	21	lead with bump same solder near (resist layer)and 257/738. ccls.	USPAT	OR	ON	2008/02/03 21:00
L29	5	("4280132"   "5953814"   "6157085"   "6287895").PN. OR ("6710458").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L30	43	("4604644"   "5084961"   "5089440"   "5121190"   "5194930"   "5274913"   "5400950"   "5542601"   "5578525"   "5615477"   "5704116"   "5710071").PN. OR ("5953814").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L31	1	"5, 656, 862".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00

L32	44	lead with substrate with bump and 257/786.ccls.	USPAT	OR	ON	2008/02/03 21:00
L33	17	lead with substrate with bump and 257/782.ccls.	USPAT	OR	ON	2008/02/03 21:00
L34	38	lead with substrate with bump and 257/783.ccls.	USPAT	OR	ON	2008/02/03 21:00
L35	88	L32 L33 L34	USPAT	OR	ON	2008/02/03 21:00
L36	88	L32 L33 L34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L37	2	"20040061240".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L38	3419	(257/778).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/03 21:00
L39	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L40	0	L39 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L41	434	L38 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L42	323	L38 and substrate with tape	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L43	88	L42 and underfill	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00

L44	180	("4604644" / "4825284" / "4970575" / "4987100" / "5107325" / "5177669" / "5222014" / "5239198" / "5249101" / "5291062" / "5311402").PN. OR ("5450283").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L45	43	L38 and surfactant	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L46	1	"6,576,495".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L47	2596	tape with substrate with made	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L48	699	L47 and "257"/\$. cc1s.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L49	12	("5918364" / "5939783" / "5985456" / "6013417" / "6044550" / "6165885" / "6281046" / "6316830" / "6319751").PN. OR ("6445075").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L50	3	(US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did.	USPAT	OR	ON	2008/02/03 21:00
L51	143	lead with substrate with bump and 257/778.cc1s.	USPAT	OR	ON	2008/02/03 21:00
L52	6	("4624724" / "5538771" / "5614316" / "5670251").PN. OR ("6498400").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00

L53	24	("2671844"   "3488840"   "4661192"   "4706811"   "4758407"   "4806309"   "5120678"   "5154341"   "5269453"   "5282565"   "5346857"   "5352407"   "5410184"   "5411703"   "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L54	20	("4706811"   "4758407"   "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L55	95	lead with substrate with bump and 257/738.ccls.	USPAT	OR	ON	2008/02/03 21:00
L56	95	lead with substrate with bump and 257/738.ccls.	USPAT	OR	ON	2008/02/03 21:00
L57	3683	(257/e23.021).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/03 21:00
L58	2	L57 and solder with resist same wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L59	0	L57 and solder near2 (resist mask) with underfill with wetab \$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L60	0	(257/e23.\$4).ccls. and solder near2 (resist mask) with underfill with wetab \$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L61	142	(257/e23.\$4).ccls. and solder near2 (resist mask) with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00

L62	136	(257/e23.\$4).ccls. and solder near2 (resist mask) and pad with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L63	52	(257/e23.\$4).ccls. and solder near2 (resist mask) same pad with underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L64	18	("4786545" / "5055321" / "5278429" / "5473512" / "5519251" / "5756380" / "5816478" / "5834832" / "5872399" / "5925403" / "6197615" / "6286207" / "6288451" / "6323542" / "6344753").PN. OR ("6806560").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L65	73038	(257/e23.\$4).ccls. antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L66	0	(257/e23.\$4).ccls. and antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L67	0	(257/e23.\$4).ccls. and antirepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L68	0	(257/e23.\$4).ccls. and nonrepellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L69	19	(257/e23.\$4).ccls. and \$5repellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00

L70	1	(257/e23.\$4).ccls. and anti near2 repellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L71	1	("257"/\$6).ccls. and anti near2 repellant	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L72	0	("257"/\$6).ccls. and solder near2 (resist mask) with underfill with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L73	0	("257"/\$6).ccls. and solder near2 (resist mask) with underfill \$3 with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L74	2	("257"/\$6).ccls. and solder near2 (resist mask) with wetab\$6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L75	28	("257"/\$6).ccls. and solder near2 (resist mask) with (improv \$3, increas\$3) with attach\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L76	4	("5703402"   "5801440"   "6329228").PN. OR ("6608388").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L77	20	("4706811"   "4758407"   "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L78	24	("2671844"   "3488840"   "4661192"   "4706811"   "4758407"   "4806309"   "5120678"   "5154341"   "5269453"   "5282565"   "5346857"   "5352407"   "5410184"   "5411703"   "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00



L79	2	"3488840".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L80	12	("4604644" / "5084961" / "5089440" / "5121190" / "5194930" / "5274913" / "5400950" / "5542601" / "5578525" / "5615477" / "5704116" / "5710071").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L81	125	("5710071").URPN.	USPAT	OR	ON	2008/02/03 21:00
L82	6	"5, 71, 071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L83	2	"5710071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L84	2	"5, 710, 071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L85	11	("4604644" / "5144747" / "5182632" / "5203076" / "5218234" / "5296738" / "5311059" / "5385869" / "5473512" / "5488200" / "5594626").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L86	111	("4138691" / "4268848" / "4280132" / "4843036" / "5001542" / "5107325").PN. OR ("5218234").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L87	3290	257/778.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L88	637	L87 and solder near2 (resist mask)	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00

L89	350	L88 and polyimide	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L90	245	L88 and polyimide	USPAT	OR	ON	2008/02/03 21:00
L91	29	("4658332" / "4740414" / "4847136" / "4847146" / "4855872" / "4873615" / "5026624" / "5110867" / "5258648" / "5262280" / "5278010" / "5304457" / "5329423" / "5391435" / "5439766" / "5439779" / "5473119" / "5493075" / "5496769" / "5511306" / "5535101" / "5579573" / "5633535" / "5801446" / "5808874" / "5821305" / "5866952" / "6002590" / "6054250").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L92	150	("4604644" / "4864470" / "4931345" / "5107325" / "5172303" / "5241133" / "5378869").PN. OR ("5535101").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L93	1809657	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polymide near3 substrate thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L94	105857	L93 and "438"/\$. cccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L95	64423	L93 and "438"/\$. cccls.	USPAT	OR	ON	2008/02/03 21:00
L96	35003	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polymide near3 substrate thickness with micrometers	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00

L97	2267	L96 and "438"/\$. ccls.	USPAT	OR	ON	2008/02/03 21:00
L98	21320	(IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness with micrometers	USPAT	OR	ON	2008/02/03 21:00
L99	347027	L98 and solder ball	USPAT	OR	ON	2008/02/03 21:00
L100	300	L98 and solder near2 ball	USPAT	OR	ON	2008/02/03 21:00
L101	13	polyimide near2 substrate with thickness with micrometers	USPAT	OR	ON	2008/02/03 21:00
L102	39	polyimide near5 substrate with thickness with micrometers	USPAT	OR	ON	2008/02/03 21:00
L103	26	L102 not L101	USPAT	OR	ON	2008/02/03 21:00
L104	7	("3948429"   "4255644"   "4300715"   "4371912"   "4607779"   "4638937"   "4638938").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L105	39	("3948429"   "4255644"   "4300715"   "4371912"   "4607779"   "4638937"   "4638938").PN. OR ("5201451").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L106	1009	thin with polyimide with substrate and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L107	639	thin with polyimide with substrate and "257"/\$.ccls.	USPAT	OR	ON	2008/02/03 21:00
L108	52	thin with polyimide with substrate with "mu.m" and "257"/\$. ccls.	USPAT	OR	ON	2008/02/03 21:00
L109	229	(IC integrated near1 circuit chip die semiconductor silicon wafer) and thin with polyimide with substrate with "mu.m"	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L110	132	L109 not "44"	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00

L111	179	L109 not L108	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L112	79	L109 not L108	USPAT; USOCR	OR	ON	2008/02/03 21:00
L113	393	(IC integrated nearl circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m"	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L114	232	(IC integrated nearl circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m"	USPAT	OR	ON	2008/02/03 21:00
L115	0	jp-361633-\$.did.	USPAT	OR	ON	2008/02/03 21:00
L116	0	jp-361633-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L117	1	jp-1361633-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L118	0	jp-11361633-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L119	2	JP-2001176918-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00

L120	20	{"20010002066" / "20010040290" / "20010054751" / "4263606" / "4676864" / "4786545" / "4963974" / "5049718" / "5060052" / "5132772" / "5139610" / "5384204" / "5844304" / "5910685" / "6028011" / "6175151" / "6262488" / "6297142").PN. OR ("6518649").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L121	18	{"20010002066" / "20010040290" / "20010054751" / "4263606" / "4676864" / "4786545" / "4963974" / "5049718" / "5060052" / "5132772" / "5139610" / "5384204" / "5844304" / "5910685" / "6028011" / "6175151" / "6262488" / "6297142").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L122	1	("6592783").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L123	17	{"4551912" / "4811081" / "4851964" / "4977441" / "5032542" / "5075252" / "5153707" / "5232532" / "5427641" / "5726491" / "5949134" / "6100112" / "6274405" / "6313526" / "6315156" / "6388888" / "6559524").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00

L124	7	("5260168" / "5378581" / "5825081" / "6313526" / "6320135" / "6388888" / "6433414").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L125	18	("20010002066" / "20010040290" / "20010054751" / "4263606" / "4676864" / "4786545" / "4963974" / "5049718" / "5060052" / "5132772" / "5139610" / "5384204" / "5844304" / "5910685" / "6028011" / "6175151" / "6262488" / "6297142").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/03 21:00
L126	2	jp-2001176918-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L127	2	"20020043713".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L128	1028	(257/797).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/02/03 21:00
L129	7	L128 and dummy near2 pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00
L130	14	L128 and mark with probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/03 21:00

2/3/08 9:50:10 PM

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